



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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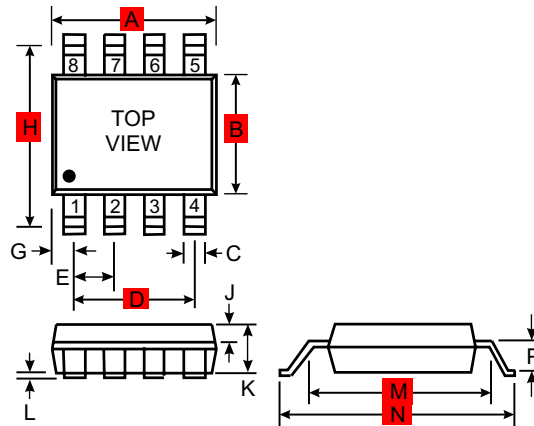
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**SINGLE P-CHANNEL ENHANCEMENT MODE
FIELD EFFECT TRANSISTOR**

Features

- High Cell Density DMOS Technology
- Lower On-State Resistance
- High Power and Current Capability
- Fast Switching Speed
- High Transient Tolerance



SO-8		
Dim	Min	Max
A	3.94	4.19
B	3.20	3.40
C	0.381	0.495
D	2.67	3.05
E	0.89	1.02
G	0.527	0.679
J	0.41 Nominal	
K	0.94	1.09
L	0.025	0.152
M	4.37	4.62
N	4.39	4.70
P	0.939 Nominal	
All Dimensions in mm		

Mechanical Data

- SO-8 Plastic Case
- Terminal Connections: See Outline Drawing and Internal Circuit Diagram above

Maximum Ratings 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current	I_D	± 3.4	A
		± 10	
Maximum Power Dissipation	P_d	2.5	W
		1.2	
		1.0	
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150	°C

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	50	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	25	°C/W

Notes: 1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance ($R_{\theta JC} + R_{\theta CA}$) where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ in this instance is 25°C/W but is dependent on the specific circuit board thermal design.

- 1a. With 1 in² of 2 oz. copper mounting pad $R_{\theta JA} = 50^\circ\text{C/W}$.
- 1b. With 0.04 in² of 2 oz. copper mounting pad $R_{\theta JA} = 105^\circ\text{C/W}$.
- 1c. With 0.006 in² of 2 oz. copper mounting pad $R_{\theta JA} = 125^\circ\text{C/W}$.

Electrical Characteristics

25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	-30	—	—	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current $T_J = 55^\circ C$	I_{DSS}	—	—	-2.0 -25	μA	$V_{DS} = -24V, V_{GS} = 0V$
Gate-Body Leakage, Forward	I_{GSSF}	—	—	100	nA	$V_{GS} = 20V, V_{DS} = 0V$
Gate-Body Leakage, Reverse	I_{GSSR}	—	—	-100	nA	$V_{GS} = -20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage $T_J = 125^\circ C$	$V_{GS(th)}$	-1.0 -0.85	-1.60 -1.25	-2.8 -2.5	V	$V_{DS} = V_{GS}, I_D = -250\mu A$
Static Drain-Source On-Resistance $T_J = 125^\circ C$	$R_{DS(ON)}$	—	0.11 0.15 0.17 0.24	0.13 0.21 0.20 0.32	Ω	$V_{GS} = -10V, I_D = -1.0A$ $V_{GS} = -10V, I_D = -1.0A$ $V_{GS} = -4.5V, I_D = -0.5A$ $V_{GS} = -4.5V, I_D = -0.5A$
On-State Drain Current	$I_{D(ON)}$	-10	—	—	A	$V_{GS} = -10V, V_{DS} = -5V$
Forward Transconductance	g_{FS}	—	4.0	—	m	$V_{DS} = -15V, I_D = -3.4A$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{ISS}	—	350	—	pF	$V_{DS} = -10V, V_{GS} = 0V$ $f = 1.0MHz$
Output Capacitance	C_{OSS}	—	260	—	pF	
Reverse Transfer Capacitance	C_{RSS}	—	100	—	pF	
SWITCHING CHARACTERISTICS (Note 2)						
Turn-On Delay Time	$t_{D(ON)}$	—	9.0	40	ns	$V_{DD} = -10V, I_D = -1.0A$ $V_{GEN} = -10V, R_{GEN} = 6.0\Omega$
Turn-On Rise Time	t_r	—	21	40	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	21	90	ns	
Turn-Off Fall Time	t_f	—	8.0	50	ns	
Total Gate Charge	Q_g	—	10	25	nC	$V_{DS} = -10V, I_D = -3.4A$ $V_{GS} = -10V$
Gate-Source Charge	Q_{gs}	—	1.6	—	nC	
Gate-Drain Charge	Q_{gd}	—	3.4	—	nC	
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Max Continuous Drain-Source Diode Forward Current	I_S	—	—	-1.9	A	
Drain-Source Diode Forward Voltage	V_{SD}	—	-0.8	-1.3	V	$V_{GS} = 0V, I_S = -1.25A$ (Note 2)
Reverse Recovery Time	t_{rr}	—	—	100	ns	$V_{GS} = 0V, I_F = -2.0A$ $di_F/dt = 100A/\mu s$
Reverse Recovery Current	I_{rr}	—	1.9	—	A	

Notes: 2. Pulse Test: Pulse width $\geq 300\mu s$, duty cycle $\leq 2.0\%$.

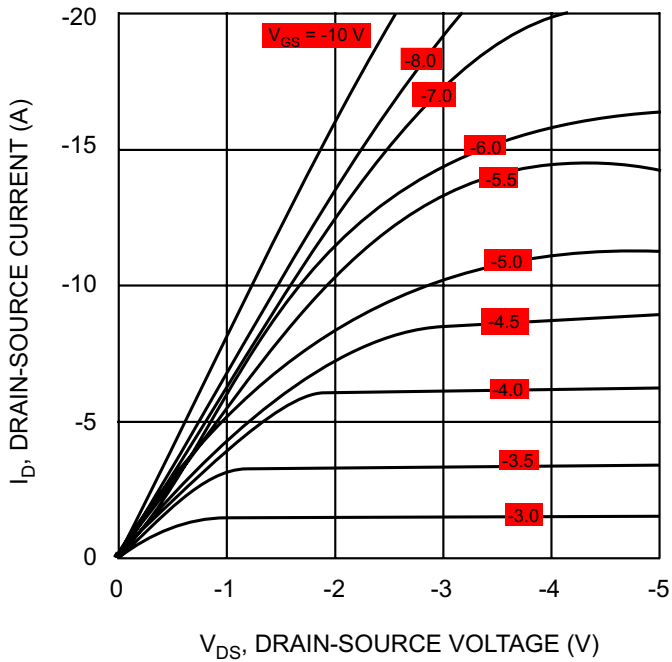


Fig. 1 On-Region Characteristics

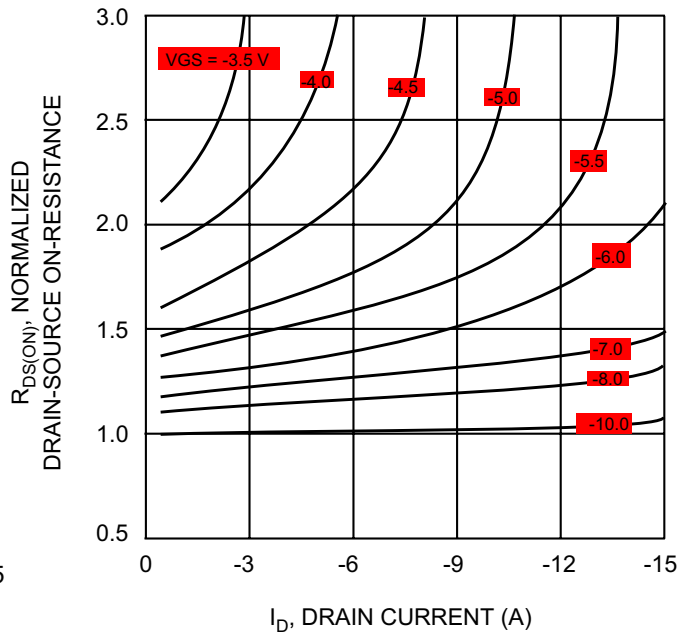


Fig. 2 On-Resistance vs Gate Voltage & Drain Current

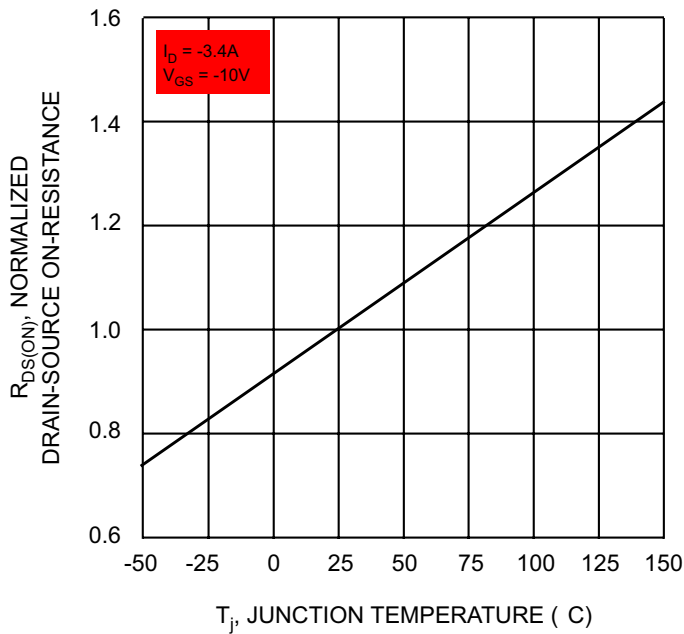


Fig. 3 On-Resistance vs Junction Temperature

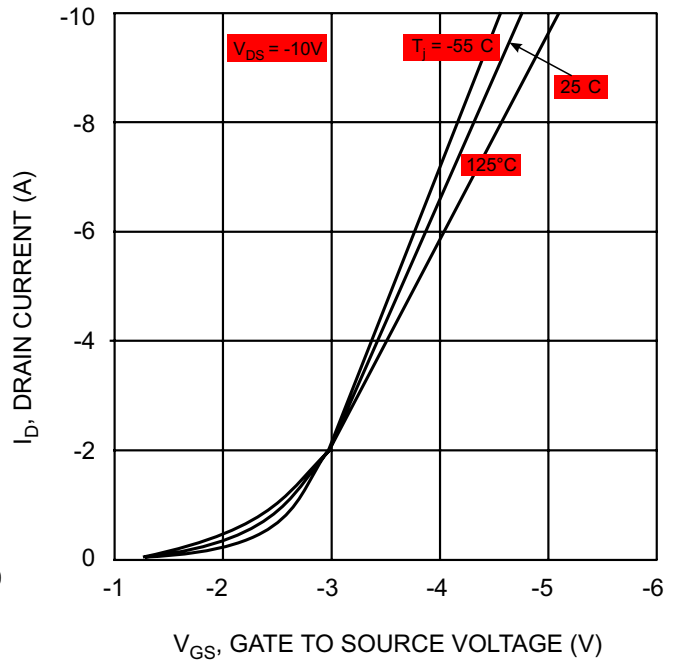
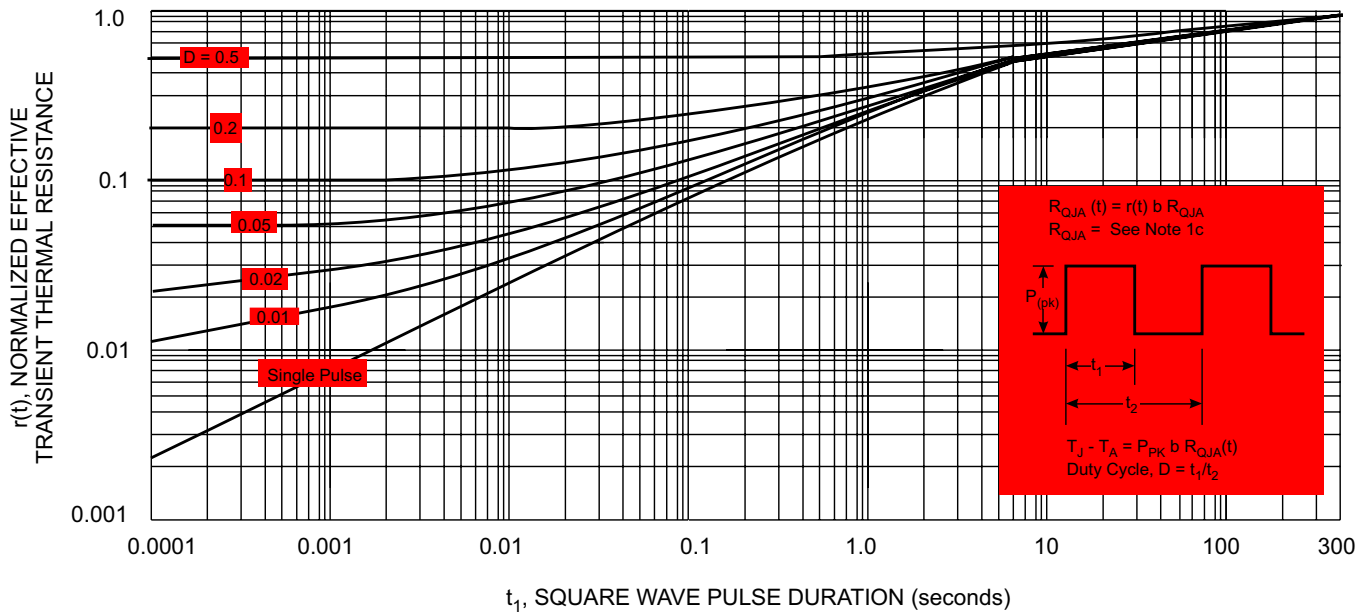
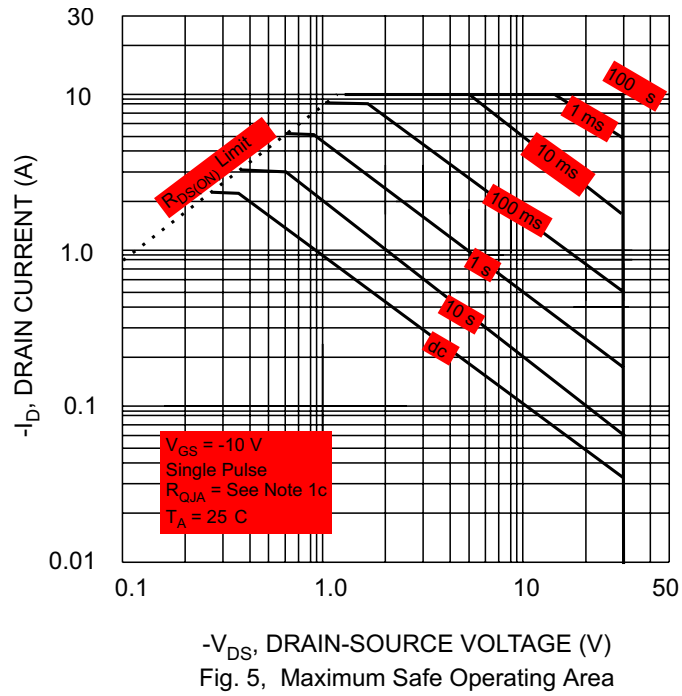


Fig. 4 Transfer Characteristics



Remark: Thermal characterization performed under conditions of Note 1c. Better thermal design such as shown in Notes 1a and 1b or 1d will offer lower R_{QJA} values and allow junction to reach thermal equilibrium sooner.